



HYSOL MG 15F-MOD2 C

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PRODUCT DESCRIPTION

HYSOL MG 15F-MOD2 C is a Green, semiconductor grade mold compound providing the following product characteristics:

Technology	Epoxy
Cure	Heat
Appearance	Black
Filler Type	Spherical Silica
Filler Weight, %	81.5
Application	Mold Compound
Target Package(s)	TO247, TO220
Product Benefits	Green semiconductor grade
Flammability Rating	UL 94 V0 @ ¼ inch thickness

HYSOL MG 15F-MOD2 C is designed for use in high voltage and high power device applications.

TYPICAL PROPERTIES OF UNCURED MATERIAL

Spiral Flow, @ 175°C, inches	43
Gel Time @ 175°C, seconds	29
Shelf Life @ 5°C, days	183
Specific Gravity, g/cm ³	1.93

TYPICAL PROCESS DATA

Handling	
Molding Temperature, °C	175 to 190
Transfer Pressure, Kg/cm ²	40 to 80
Transfer Time, seconds	10 to 20
Curing Time, seconds	150 to 200
Post Mold Cure @ 175 to 190 °C, hours	2 to 6

HYSOL MG 15F-MOD2 C has been formulated to provide the best possible moldability and as wide a molding latitude as possible. Although molding and curing conditions will vary from situation to situation, recommended starting ranges are shown above.

Please contact Henkel Technical Service for alternative process parameters if needed.

TYPICAL PROPERTIES OF CURED MATERIAL

Physical Properties

Hot Hardness, Shore D, after 90 seconds	82
Glass Transition Temperature (T _g) by TMA, °C	236
Coefficient of Thermal Expansion, ppm/°C:	
Below T _g	15
Above T _g	42
Flexural Modulus @ 25°C	N/mm ² 16,636
Flexural Strength @ 25°C	N/mm ² 133

Extractable Ionic Content, ppm:

Chloride (Cl ⁻)	5.37
Sodium (Na ⁺)	5.07
Potassium (K ⁺)	2.4

DMA Modulus:

@ 25°C	N/mm ²	19,909
@ 175°C	N/mm ²	14,662
@ 260°C	N/mm ²	5,440

Application Specific Properties

Thermal Conductivity, W/(m-K)	0.78
Volume resistivity @ 21°C, 250 V, Ω-cm	38×10 ¹⁵
Dielectric Constant / Dissipation Factor @ 1 MHz	3.5 / 5.4

GENERAL INFORMATION

For safe handling information on this product, consult the Material Safety Data Sheet, (MSDS).

Not for product specifications

The technical data contained herein are intended as reference only. Please contact Hysol Huawei Electronics Co., Ltd. quality department for assistance and recommendations on specifications for this product.

Storage

Store product in the unopened container in a dry location. Storage information may be indicated on the product container labeling.

Mold Compound materials should be stored at 5°C or below, in closed containers. After removal from cold storage, the material MUST be allowed to come to room temperature, in the sealed container, to avoid moisture contamination. The suggested waiting time for a standard 15 kg carton box is 24 hours.

Material removed from containers may be contaminated during use.

Do not return product to the original container. Hysol Huawei Electronics Co., Ltd. cannot assume responsibility for product which has been contaminated or stored under conditions other than those previously indicated. If additional information is required, please contact Hysol Huawei Electronics Co., Ltd. Technical Service Center or Customer Service Representative.

Disclaimer**NOTE**

The information provided in this Technical Data Sheet (TDS) including the recommendations for use and application of the product are based on our knowledge and experience of the product as at the date of this TDS. The product can have a variety of different applications as well as differing application and working conditions in your environment that are beyond our control. Hysol Huawei is, therefore, not liable for the suitability of our product for the production processes and conditions in respect of which you use them, as well as the intended applications and results. We strongly recommend that you carry out your own prior trials to confirm such suitability of our product.

Any liability in respect of the information in the Technical Data Sheet or any other written or oral recommendation(s) regarding the concerned product is excluded, except if otherwise explicitly agreed and except in relation to death or personal injury caused by our negligence and any liability under any applicable mandatory product liability law.

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